

ABSTRACT OF THE DISCLOSURE

Provide a discrete semiconductor device, particularly a discrete semiconductor device for small signal operation with a smaller packaging area and has excellent high frequency characteristics and good heat dissipation performance, and a method for producing the same. The discrete semiconductor elements are mounted on die bond pads and wire bond pads with the packaging surface being sealed with a resin, and connecting the back faces of the die bond pads and the wire bond pads directly to a mother board.

故其後人多以爲非也。蓋其後人不知其所以爲非也。故其後人多以爲非也。